



Product Information

Lead-free electronic solder FELDER-ISO-Tin® “Sn96Ag + REFILL”

Lead-free refill solder for wave and selective soldering units

Sn96.9Ag3NiGe according to Fuji-Pat. No. DE19816671C2, US6179.935, JP3296289

Item No.: 551277....

All information about our products is the result of our long standing experience which we would like to pass on to our customers as application support. However, as we do not have any influence on the application of the works carried out with our products, please see the warranty claims in our conditions of sale because our liability is limited.

This product information does not constitute warranted properties.

Application

In order to compensate the entry of copper into the lead-free alloy Sn96Ag+ in wave soldering and selective soldering units we recommend Sn96Ag+ Refill. Hereto a regular control of the solder bath is unavoidable.

Properties

As most of the PCBs and components have copper-plated conducting paths and connections copper is flushed into the solder bath by the soldering process. In fact Sn96Ag+ has a lower dealloying quote of copper as other lead-free solders, nevertheless a copper level compensation is necessary.

Alloy: Sn96.93Ag3.0NiGe

Melting point: reduces in the solder bath to 217 – 220 ° C!

Analysis / tolerances

Element	Sn	Cu	Ag	Ni	Ge	Pb	Al
Content (%)	rest	0.05	3.0 ±0,2	0.05 - 0.07	0.01 – 0.015	max. 0.07	max. 0.001

Element	As	Bi	Cd	Fe	Sb	Zn
Content (%)	max. 0.03	max. 0.1	max. 0.002	max. 0.02	max. 0.1	max. 0.001

acc.: DIN EN 9453:2014

Delivery Forms

450 g (± 30 g) rods, 330 x 20 x 10 mm,
1.0 kg rods, 330 x 20 x 20 mm,
3.5 kg – blocks with hanging hole 545 x 47 x 20 mm.

Also deliverable as massive wire on spools and wire cuts for first filling.

Advices

Other alloys are included in our standard delivery program.